



# Press Release

Nippon Chemi-Con Corporation  
April 8, 2016

## **Resin-Molded Chip Type Conductive Polymer Aluminum Solid Capacitors PMA Series With a Low Profile of 3.0mm**

Nippon Chemi-Con has added 3.0mm max. low-profile products to the resin-molded chip type conductive polymer aluminum solid capacitors PMA Series.

We have reviewed the conventional structure in which the element is sealed with an aluminum case and sealing rubber and developed a unique technology to seal the element with resin mold instead. The technology has already been commercialized as the PMA Series.

The case size of existing products is 7x7x3.5 mm max. However, we have succeeded in further reducing the height to 3.0mm max. By newly reviewing the terminal structure and resin, we have reduced the height while maintaining the same performance and reliability as 3.5mm max. products. As a result, this product can be mounted on even smaller and thinner devices.

Samples of the 3.0mm max. product have been available since April this year, and mass production is scheduled to begin this October.

We will continue to work on the development of high-capacitance products, 35V products (currently up to 25V), and products guaranteeing moisture-resistance at 85°C85%RH to expand the variation of the resin-molded chip type PMA Series.

### [Main Specifications]

- Category temperature range: -55°C to +105°C
- Rated voltage range: 6.3V to 25V
- Capacitance range: 22 to 220μF
- Endurance: guarantees 5,000 hours at 105°C  
guarantees 500 hours at 65°C95%RH
- Equivalent series resistance (ESR): 35 to 50mΩ
- Allowable ripple current: 2000 to 2300 mArms
- Case size: 7x7x3.0mm Max

### [Samples and Mass Production]

Samples: April 2016

Mass production: October 2016

### [Production Site]

Chemi-Con Yonezawa Corp.

[Product Appearance]

